DRC4152Z

Silicon NPN epitaxial planar type

For digital circuits Complementary to DRA4152Z DRC2152Z in NS through hole type package

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

Packaging

DRC4152Z0A Radial type : 5000 pcs / carton

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	50	V	
Collector-emitter voltage (Base open)	V _{CEO}	50	V	
Collector current	I _C	100	mA	
Total power dissipation	P _T	300	mW	
Junction temperature	Tj	T _j 150		
Storage temperature	T _{stg}	-55 to +150	°C	

Package

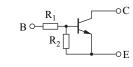
- Code
- NS-B2-B-B
 - Package dimension clicks here. $\!\!\!\!\rightarrow$

• Pin Name

- 1: Emitter
- 2: Collector
- 3: Base

Marking Symbol: N0

Internal Connection



Resistance value	R ₁	0.51	kΩ
	R ₂	5.1	kΩ

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu {\rm A}, I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 50 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 V, I_C = 0$			2.0	mA
Forward current transfer ratio	$h_{\rm FE}$	$V_{CE} = 10 \text{ V}, I_C = 5 \text{ mA}$	20			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.5 \text{ mA}$			0.25	V
Input voltage (ON)	V _{I(on)}	$V_{\rm CE} = 0.2$ V, $I_{\rm C} = 5$ mA	1.0			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = 5 \text{ V}, I_C = 100 \mu\text{A}$			0.4	V
Input resistance	R ₁		-30%	0.51	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.08	0.10	0.12	

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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